

800V SiC N-Channel MOSFET

MAIN CHARACTERISTICS

I_D	53A
V_{DS}	800V
R_{DS(on)-typ} (@V _{GS} =18V T _C =25°C)	<73mΩ(Typ:53mΩ)

FEATURES

- ◆High Speed Switching with Low Capacitances
- ◆High Blocking Voltage with Low RDS(on)
- ◆Easy to Parallel
- ◆Simple to Drive
- ◆RoHS Compliant

BENEFITS

- ◆Increased Power Density
- ◆Faster Operating Freequenc
- ◆Reduction of Heat Sink Requirements
- ◆Higher Efficiency
- ◆Reduced EMI

APPLICATIONS

- ◆Power Factor Correction Modules
- ◆Switch Mode Power Supplies
- ◆DC-AC Inverters
- ◆High Voltage DC/DC Converters

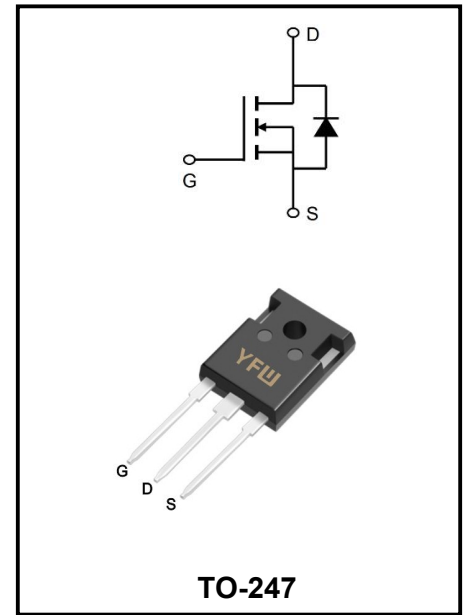
MECHANICAL DATA

- ◆Case: TO-247/AP
- ◆Mounting Position: Any
- ◆Molded Plastic: UL Flammability Classification Rating 94V-0
- ◆Lead free in compliance with EU RoHS 2011/65/EU directive
- ◆Solder bath temperature 275°C maximum,10s per JESD 22-B106

Maximum Ratings at T_c=25°C unless otherwise specified

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	800	V
Gate-Source Voltage	V_{GS}	-8/+22	V
Recommended Operation Value	V_{GSop}	-4/+18	V
Continue Drain Current T _c =25°C	I_D	53	A
Continue Drain Current T _c =100°C		28	
Pulsed Drain Current	I_{DM}	80	A
Power Dissipation TC=25°C	P_D	98	W
Operating Temperature Range	T_J	-40 to +175	°C
Storage Temperature Range	T_{STG}	-40 to +175	°C
Thermal Resistance, Junction to Case	R_{θJC}	1.1	°C/W
Thermal Resistance, Junction to Ambient	R_{θJA}	40	°C/W

Note1:Pulse test: 300 μs pulse width, 2 % duty cycle



Electrical Characteristics at Tc=25°C unless otherwise specified

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100\mu A$	BV_{DSS}	800	-	-	V
Drain-Source Leakage Current	$V_{DS} = 800V, V_{GS} = 0V$	I_{DSS}	-	1	-	μA
Gate Leakage Current	$V_{GS} = +18V, V_{DS} = 0V$	I_{GSS}	-	-	250	nA
	$V_{GS} = -4V, V_{DS} = 0V$		-	-	-250	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 5mA$	V_{GS(th)}	2	2.7	4	V
Drain-Source On-State Resistance	$V_{GS} = 18V, I_D = 20A$	R_{DS(on)}	-	53	73	mΩ
	$V_{GS} = 18V, I_D = 20A, T_J = 175^\circ C$		-	58	-	mΩ
Internal Gate Resistance	f=1MHz	RG	-	2.1	-	Ω
Input Capacitance	$V_{DS}=600V$ $V_{GS}=0V$ f=1MHz	C_{iss}	-	1301	-	pF
Output Capacitance		C_{oss}	-	138	-	
Reverse Transfer Capacitance		C_{rss}	-	14	-	
Total Gate Charge(Note2)	$I_D = 20A$ $V_{DD}=400V$ $V_{GS} = -4/+ 18V$	Q_g	-	68	-	nC
Gate to Source Charge(Note2)		Q_{gs}	-	17	-	
Gate to Drain Charge(Note2)		Q_{gd}	-	22	-	
Turn-on Delay Time(Note2)	$V_{DS} = 400V, I_D=20A,$ $V_{GS} = -4/+18V,$ $R_G = 2.5\Omega$ $L=200\mu H$	t_{d(on)}	-	13	-	ns
Rise Time(Note2)		t_r	-	20	-	
Turn-Off Delay Time(Note2)		t_{d(OFF)}	-	20	-	
Fall Time(Note2)		t_f	-	9	-	
Turn-on Switching Energy		E_{on}	-	108	-	
Turn-off Switching Energy	E_{off}	-	35	-	μJ	
Maximun Body-Diode Continuous Current	$V_{GS} = -4V, T_C=25^\circ C$	I_S	-	33	-	A
	$V_{GS} = -4V, T_C=100^\circ C$		-	18	-	A
Maximun Body-Diode Pulsed Current(Note2)		I_{SM}	-	-	80	A
Drain-Source Diode Forward Voltage	$V_{GS}=-4V, I_{SD}=10A T_J=25^\circ C$	V_{SD}	-	4.6	-	V
	$V_{GS}=-4V, I_{SD}=10A T_J=175^\circ C$		-	4	-	V
	$V_{GS}=-4V, I_{SD}=20A T_J=25^\circ C$		-	5.4	-	V
	$V_{GS}=-4V, I_{SD}=20A T_J=175^\circ C$		-	4.6	-	V
Reverse Recovery Time(Note2)	$V_{GS} = -4V, I_{SD}= 20A, V_R=400V$ di/dt=989A/μs	trr	-	18	-	ns
Reverse Recovery Charge(Note2)		Qrr	-	104	-	nC
Peak Reverse Recovery Current		Irrm	-	10.2	-	A

Note2:Pulse test: 300 us pulse width,2 % duty cycle

RATINGS AND CHARACTERISTIC CURVES

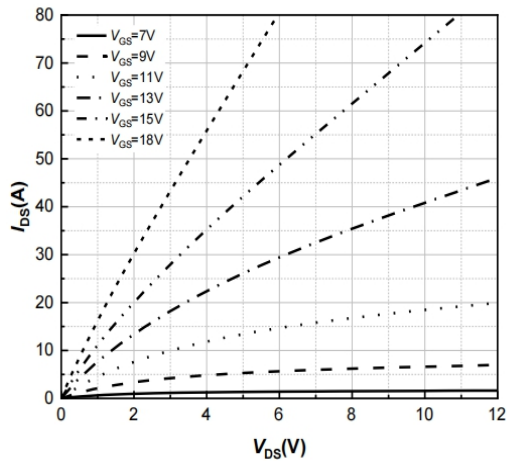


Figure 1. Output Characteristics
 $T_j = -40^\circ\text{C}$

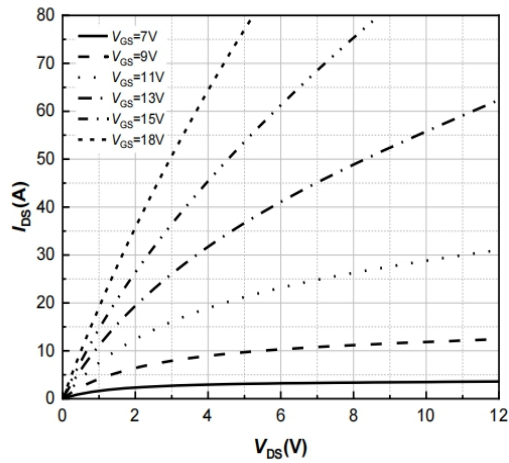


Figure 2. Output Characteristics
 $T_j = 25^\circ\text{C}$

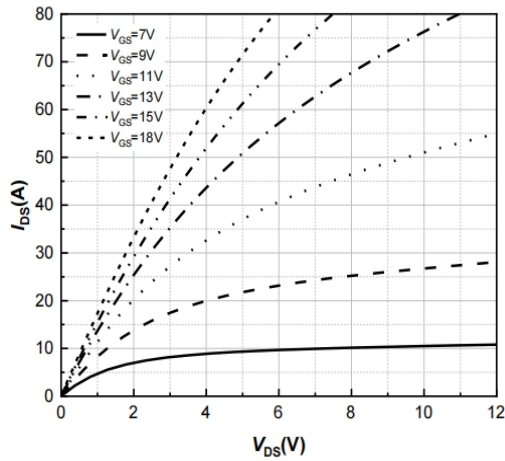


Figure 3. Output Characteristics
 $T_j = 175^\circ\text{C}$

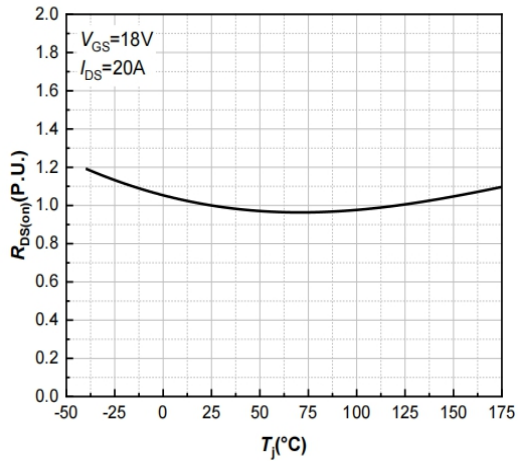


Figure 4. Normalized On-Resistance vs. Temperature

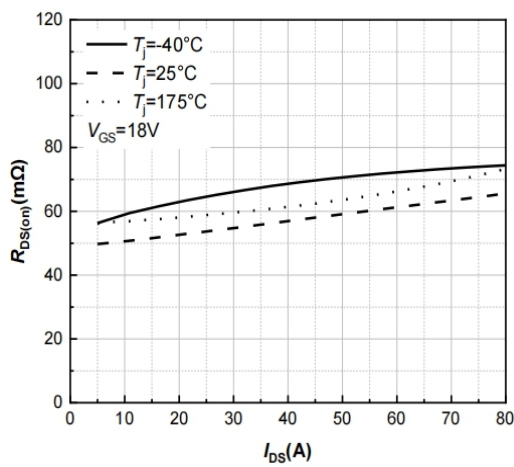


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

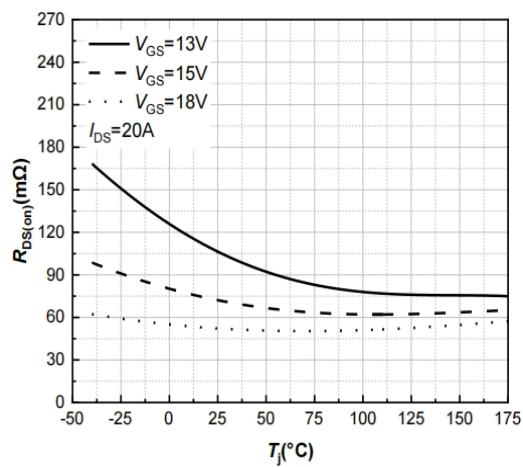


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

RATINGS AND CHARACTERISTIC CURVES

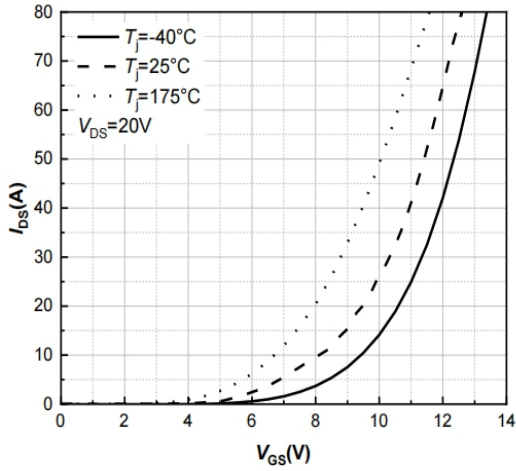


Figure 7. Transfer Characteristic for Various Junction Temperatures

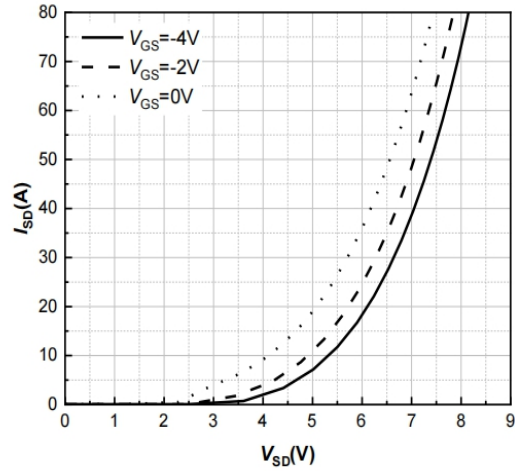


Figure 8. Body Diode Characteristic $T_J = -40^\circ\text{C}$

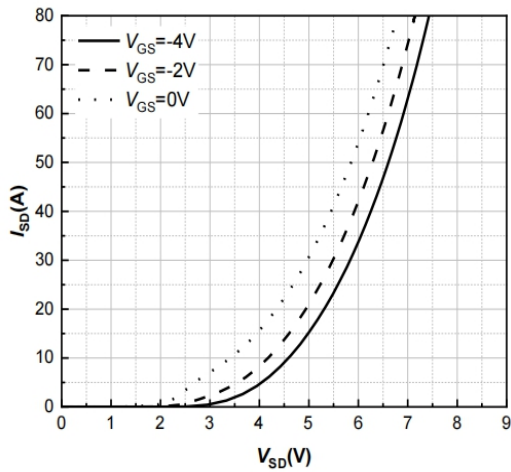


Figure 9. Body Diode Characteristic $T_J = 25^\circ\text{C}$

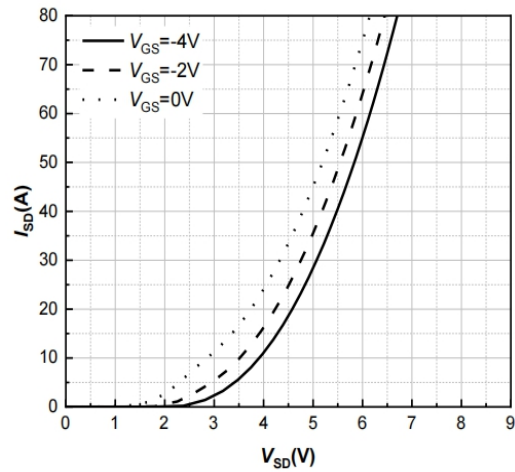


Figure 10. Body Diode Characteristic $T_J = 175^\circ\text{C}$

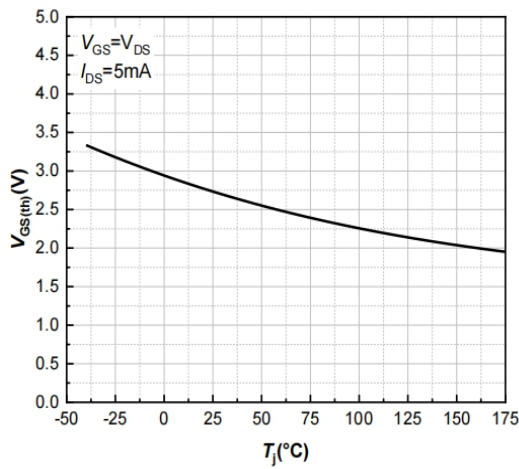


Figure 11. Threshold Voltage vs. Temperature

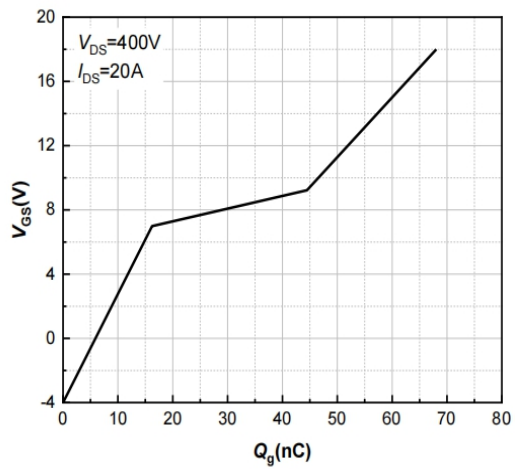


Figure 12. Gate Charge Characteristics

RATINGS AND CHARACTERISTIC CURVES

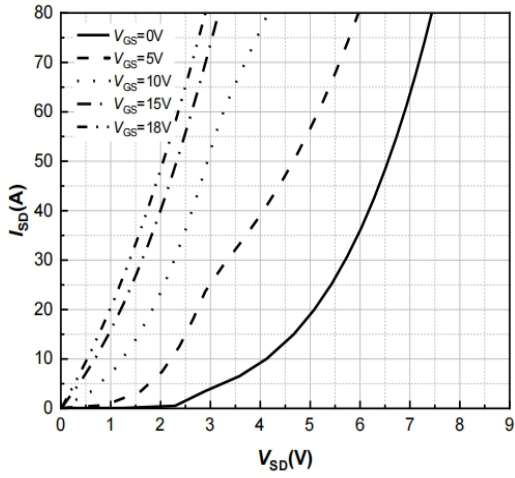


Figure 13. 3rd Quadrant Characteristic
 $T_j = -40^\circ\text{C}$

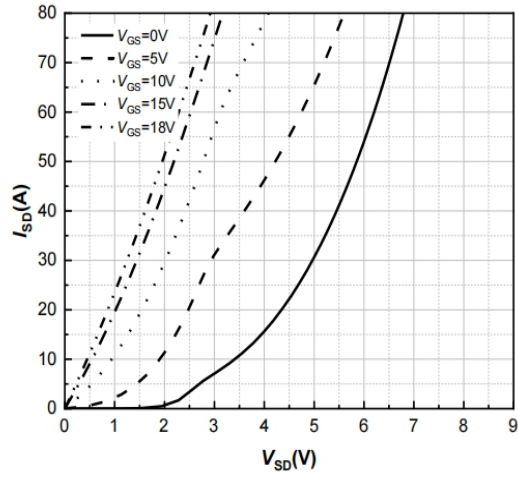


Figure 14. 3rd Quadrant Characteristic
 $T_j = 25^\circ\text{C}$

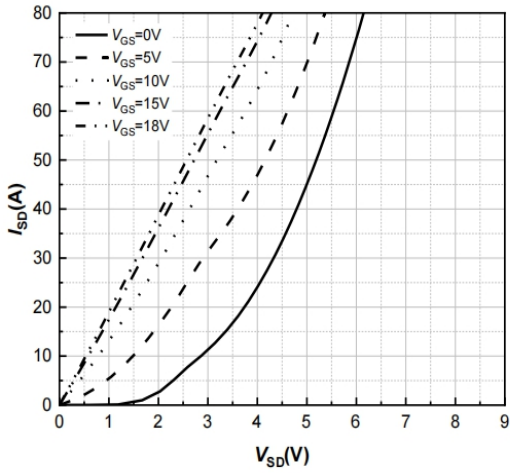


Figure 15. 3rd Quadrant Characteristic
 $T_j = 175^\circ\text{C}$

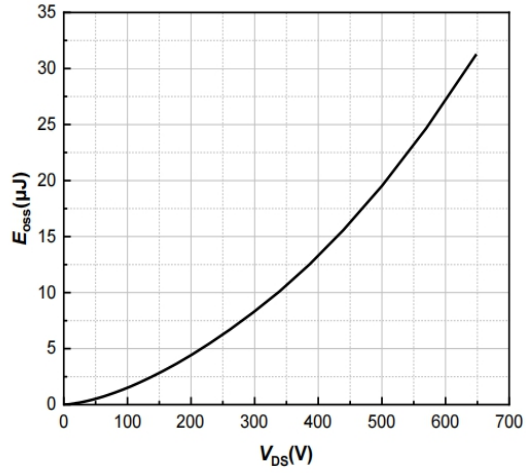


Figure 16. Output Capacitor Stored Energy

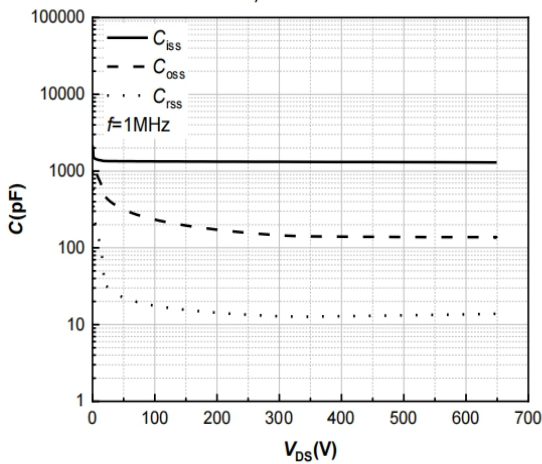


Figure 17. Capacitances vs. Drain-Source

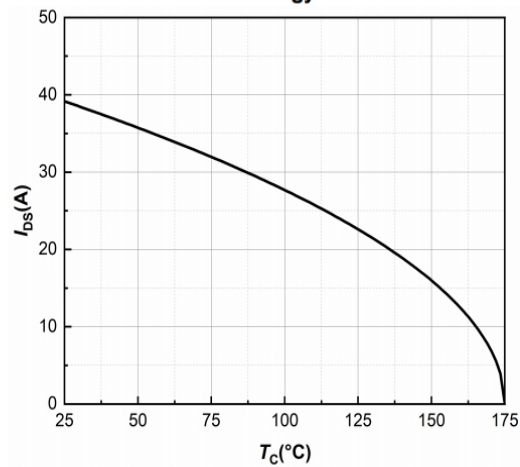


Figure 18. Continuous Drain Current Derating vs. Case Temperature

RATINGS AND CHARACTERISTIC CURVES

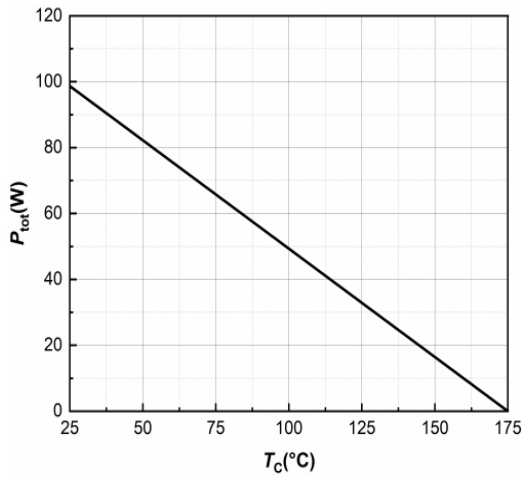


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

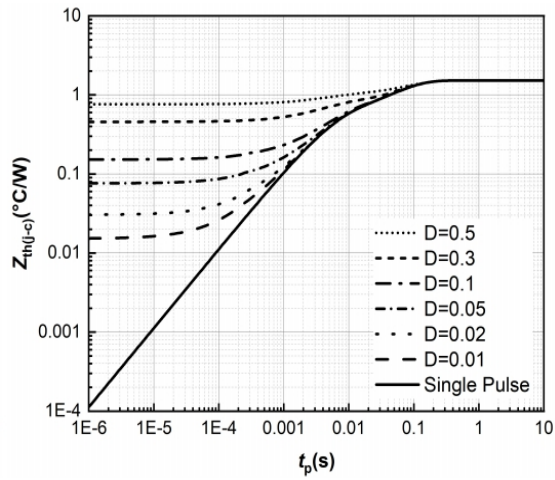


Figure 20. Transient Thermal Impedance

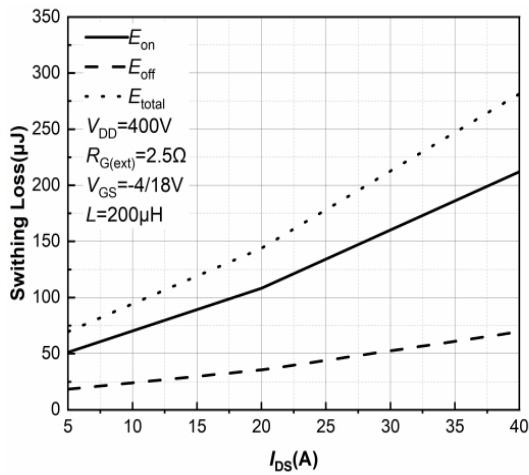


Figure 21. Clamped Inductive Switching Energy vs. Drain Current

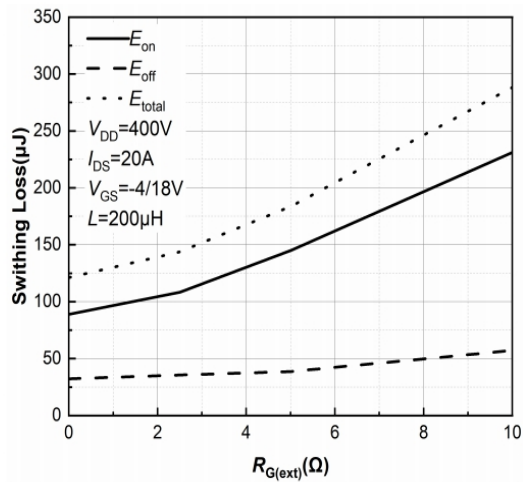


Figure 22. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

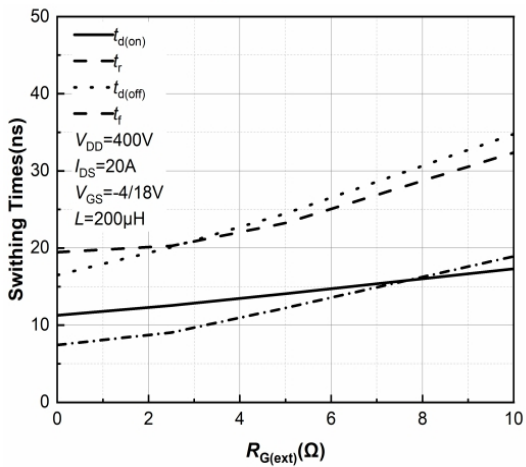


Figure 23. Switching Times vs. $R_{G(ext)}$

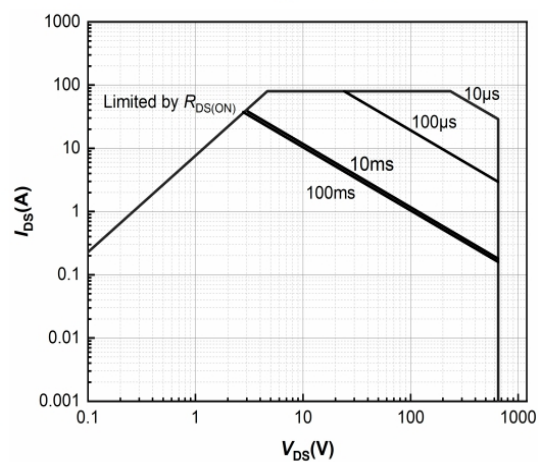
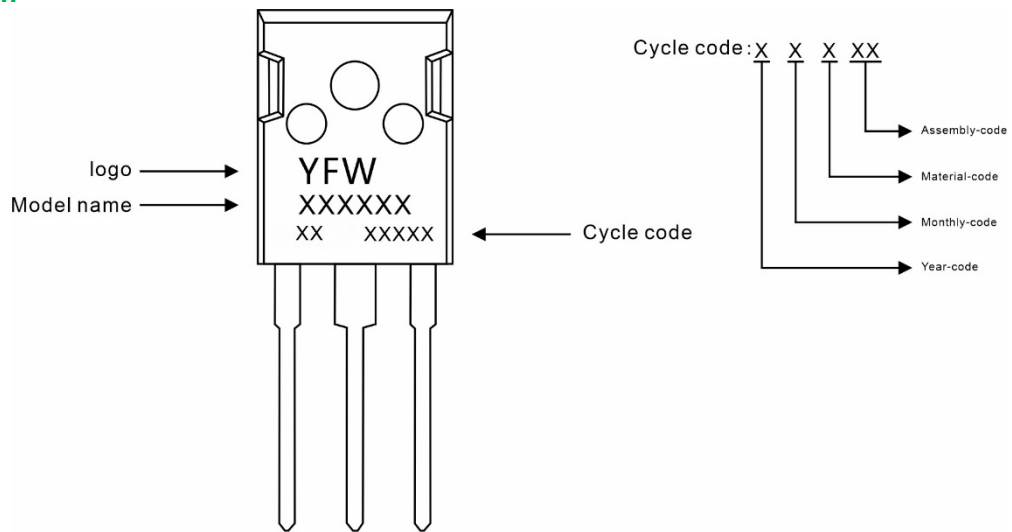


Figure 24. Safe Operating Area

Marking Diagram



Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFWM305365APG3	TO-247	0.209oz(5.93g)	30pcs/tube	600PCS/Box 2400PCS/Carton

Package Dimensions

TO-247

Symbol	Dimensions in mm		Dimensions in Inch	
	Min.	Max.	Min.	Max.
A	4.90	5.10	0.193	0.201
A1	1.90	2.10	0.075	0.083
A2	2.29	2.54	0.090	0.100
b	1.00	1.40	0.039	0.055
b1	2.00	2.20	0.079	0.087
b2	3.00	3.20	0.118	0.126
c	0.50	0.70	0.020	0.028
D	15.75	16.05	0.620	0.632
E	20.20	20.80	0.795	0.819
e	5.45 (BSC)		0.215 (BSC)	
e1	10.90 (BSC)		0.429 (BSC)	
F	6.05	6.25	0.238	0.246
F1	5.80	6.00	0.228	0.236
L	20.10	20.40	0.791	0.803
L1	4.05	4.35	0.159	0.171
Φ	3.50	3.70	0.138	0.146

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